MICROWAVE POWER GaAs FET

Low Distortion Internally Matched Power GaAs FETs (C-Band)

Features

- Low intermodulation distortion
- $IM_3 = -45 \text{ dBc}$ at Po = 25 dBm,
- Single carrier level
- High power
- P_{1dB} = 36 dBm at 6.4 GHz to 7.2 GHz
- High gain
 - $G_{1dB} = 8.0 \text{ dB}$ at 6.4 GHz to 7.2 GHz
- Broad band internally matched
- · Hermetically sealed package

RF Performance Specifications (Ta = 25° C)

Characteristics	Symbol	Condition	Unit	Min.	Тур.	Мах
Output Power at 1dB Compression Point	P _{1dB}		dBm	35.0	36.0	-
Power Gain at 1dB Compression Point	G _{1dB}	V _{DS} = 10V f = 6.4 ~ 7.2 GHz	dB	7.0	8.0	_
Drain Current	I _{DS1}		А	_	1.1	1.5
Gain Flatness	ΔG		dB	-	-	±0.6
Power Added Efficiency	η_{add}		%	_	30	_
3rd Order Intermodulation Distortion	IM ₃	Note 1	dBc	-42	-45	-
Drain Current	I _{DS2}		А	-	1.1	1.5
Channel-Temperature Rise	ΔT_{ch}	V _{DS} xI _{DS} xR _{th} (c-c)	°C	_	-	80

Electrical Characteristics (Ta = 25° C)

Characteristic	Symbol	Condition	Unit	Min.	Тур.	Мах
Trans-conductance	gm	V _{DS} = 3V I _{DS} = 1.5A	mS	_	900	-
Pinch-off Voltage	V _{GSoff}	$V_{DS} = 3V$ $I_{DS} = 20mA$	V	-2	-3.5	-5.0
Saturated Drain Current	I _{DSS}	$V_{DS} = 3V$ $V_{GS} = 0V$	A	_	2.9	3.8
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} = -60μA	V	-5	_	-
Thermal Resistance	R _{th (c-c)}	Channel to case	°C/W	_	4	6

Note 1: 2 tone Test Pout = 25dBm Single Carrier Level.

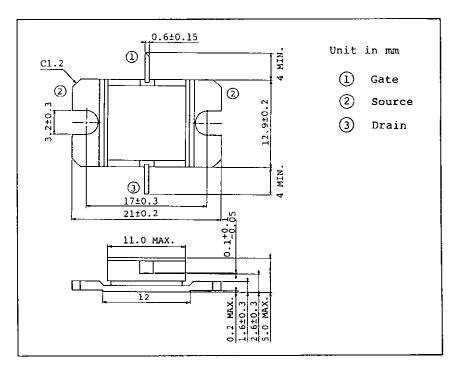
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Absolute Maximum Ratings (Ta = 25° C)

Characteristic	Symbol	Unit	Rating
Drain-Source Voltage	V _{DS}	V	15
Gate-Source Voltage	V _{GS}	V	-5
Drain Current	I _{DS}	А	4
Total Power Dissipation ($T_c = 25^{\circ}C$)	P _T	W	20
Channel Temperature	T _{ch}	°C	175
Storage Temperature	T _{stg}	°C	-65~175

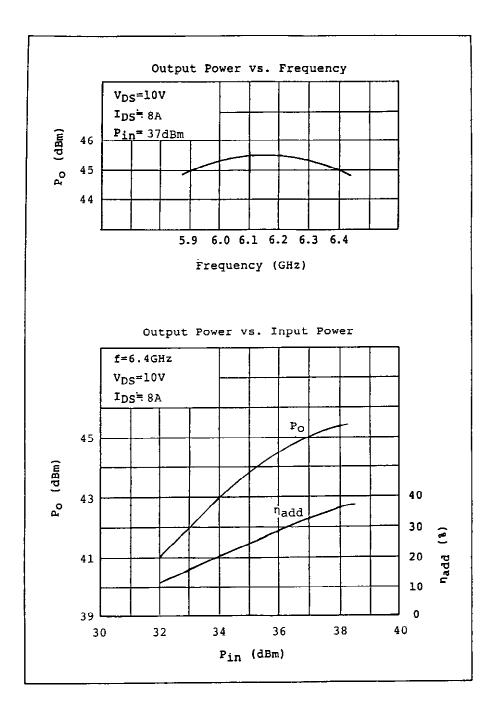
Package Outline (2-11D1B)



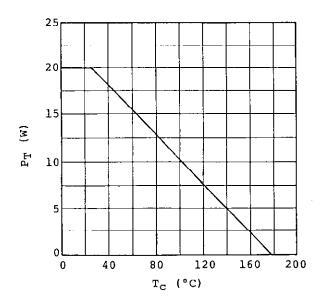
Handling Precautions for Packaged Type

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

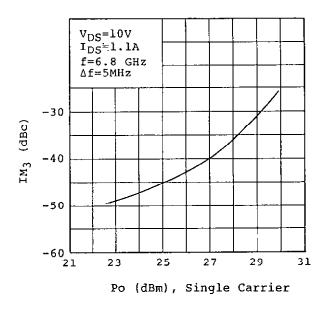
RF Performances



Power Dissipation vs. Case Temperature



IM₃ vs. Output Power Characteristics



TIM5964-4L S-Parameters (MAGN. and ANGLES)

